



Material Composition Declaration

EPC2024

Company Name	Efficient Power Conversion (EPC)	Issue Date:	7/12/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	25.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	21.8755	87.37	89.71	873719
	Silicon oxide	7631-86-9	0.0844	0.34		3372
	Silicon nitride	12033-89-5	0.0273	0.11		1091
	Gallium nitride	25617-97-4	0.1032	0.41		4121
	Aluminum	7429-90-5	0.1698	0.68		6783
	Aluminum nitride	24304-00-5	0.0248	0.10		992
	Titanium	7440-32-6	0.0049	0.02		194
	Titanium nitride	25583-20-4	0.0162	0.06		647
	Copper	7440-50-8	0.0056	0.02		225
	Tungsten	7440-33-7	0.0080	0.03		321
	Polyimide		0.1407	0.56		5622
Under Bump Metal	Titanium	7440-32-6	0.0037	0.01	1.23	146
	Nickel	7440-02-0	0.1086	0.43		4336
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1966	0.79		7851
Solder Bump	Tin	7440-31-5	2.2112	8.83	9.06	88317
	Silver	7440-22-4	0.0567	0.23		2265
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			25.0	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.